

### General Description

The 9SBV0802 provides two banks of four 1.05V LVCMOS outputs. Each bank has its own input. There are three OE pins. Two OE pins control two outputs each and one OE pin controls four outputs. One 9SBV0802 allows one PCH to easily support four CPU's with point to point routing of the PM signals. Two 9SBV0802's allow one PCH to easily support up to eight CPU's with point-to-point routing of the PM signals.

### Features/Benefits

- 1.8V Power supply, 15mW typical power consumption; eliminate thermal concerns
- OE pins; support 1, 2, 3 or 4 socket systems
- 1.05V LVCMOS inputs with VREF pin; input thresholds matched to chipset power supply
- Space saving 20-pin 4x4mm VFQFPN; minimal board space

### Recommended Application

Fanout buffer for PM-SYNC and PM\_SYNC CLK in Intel Servers

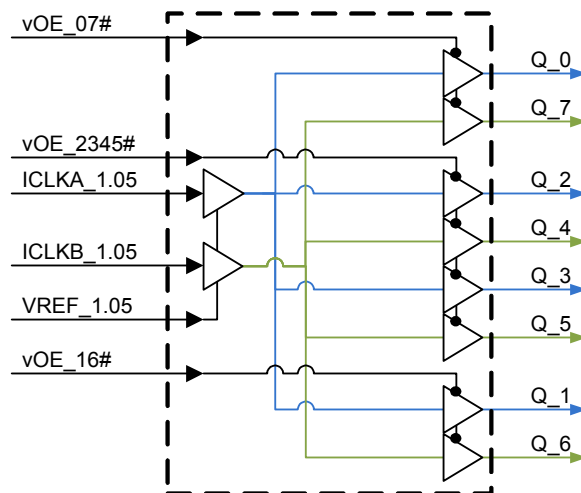
### Output Features

- 8 – 1-48MHz 1.05V LVCMOS outputs

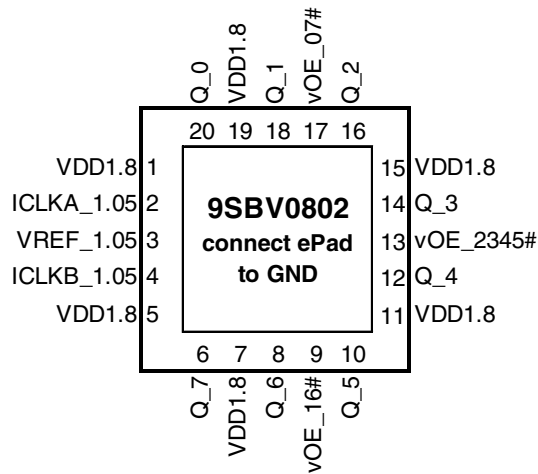
### Key Specifications

- Additive cycle-to-cycle jitter <8ps
- Output-to-output skew within a bank <50ps
- Output-to-output skew between banks <100ps

### Block Diagram



## Pin Configuration



### 20-pin VFQFPN, 4x4 mm, 0.5mm pitch

^ prefix indicates internal 120KOhm pull up resistor  
v prefix indicates internal 120KOhm pull down resistor

## Output Control Table

ICLKA_1.05 ICLKB_1.05	OE_07	OE_16	OE_2345	Q_7	Q_6	Q_5	Q_4	Q_3	Q_2	Q_1	Q_0
X	X	X	X	X	X	X	X	X	X	X	X
Running	1	1	1	0	0	0	0	0	0	0	0
Running	1	1	0	0	0	Run	Run	Run	Run	0	0
Running	1	0	1	0	Run	0	0	0	0	Run	0
Running	1	0	0	0	Run	Run	Run	Run	Run	Run	0
Running	0	1	1	Run	0	0	0	0	0	0	Run
Running	0	1	0	Run	0	Run	Run	Run	Run	0	Run
Running	0	0	1	Run	Run	0	0	0	0	Run	Run
Running	0	0	0	Run	Run	Run	Run	Run	Run	Run	Run

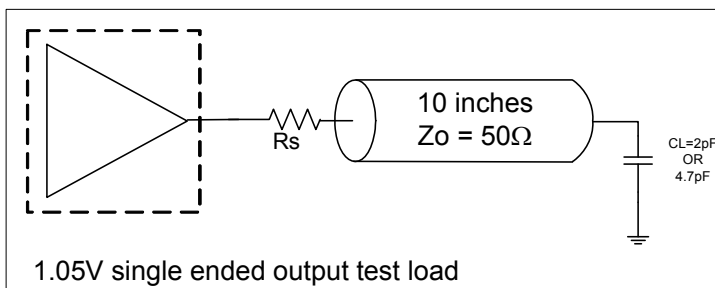
## Power Connections

Description	Pin Number	
	VDD	GND
Input Circuits	1,5	21
1.05V reference	3	21
Outputs	7,11, 15,19	21

## Pin Descriptions

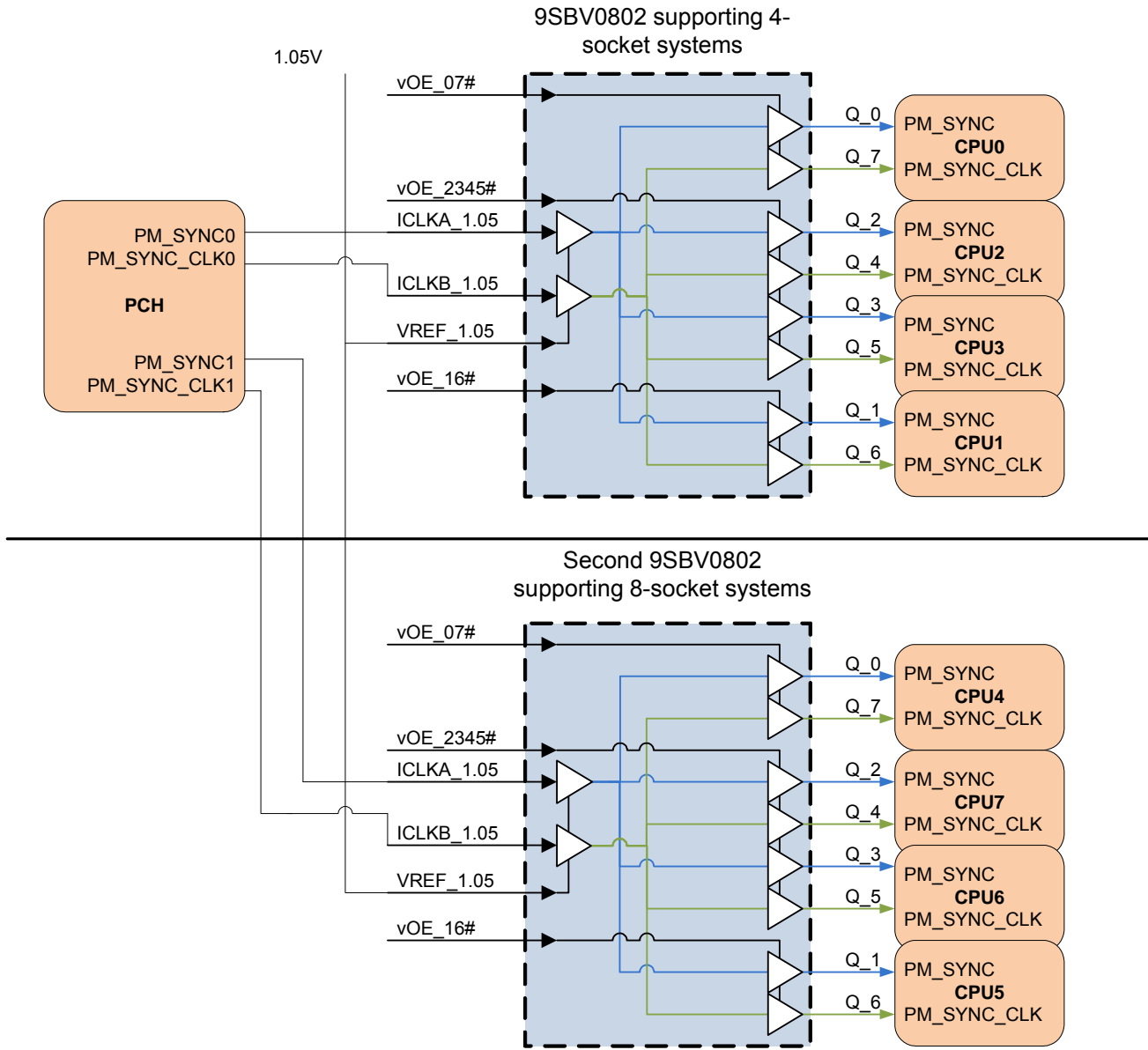
Pin#	Pin Name	Type	Pin Description
1	VDD1.8	PWR	Power supply, nominal 1.8V
2	ICLKA_1.05	IN	1.05V LVCMOS single-ended input clock. Voltage reference is set by the VREF_1.05 pin.
3	VREF_1.05	IN	Voltage reference for 1.05V single-ended inputs. Connect the VDDIO 1.05V power rail from chipset to this pin.
4	ICLKB_1.05	IN	1.05V LVCMOS single-ended input clock. Voltage reference is set by the VREF_1.05 pin.
5	VDD1.8	PWR	Power supply, nominal 1.8V
6	Q_7	OUT	LVCMOS single-ended output
7	VDD1.8	PWR	Power supply, nominal 1.8V
8	Q_6	OUT	LVCMOS single-ended output
9	vOE_16#	IN	Active low input for enabling outputs 1 and 6. This pin has an internal 120Kohm pull down. 0 = enable outputs, 1 = disable outputs
10	Q_5	OUT	LVCMOS single-ended output
11	VDD1.8	PWR	Power supply, nominal 1.8V
12	Q_4	OUT	LVCMOS single-ended output
13	vOE_2345#	IN	Active low input for enabling outputs 2 through 5. This pin has an internal 120Kohm pull down. 0 = enable outputs, 1 = disable outputs
14	Q_3	OUT	LVCMOS single-ended output
15	VDD1.8	PWR	Power supply, nominal 1.8V
16	Q_2	OUT	LVCMOS single-ended output
17	vOE_07#	IN	Active low input for enabling outputs 0 and 7. This pin has an internal 120Kohm pull down. 0 = enable outputs, 1 = disable outputs
18	Q_1	OUT	LVCMOS single-ended output
19	VDD1.8	PWR	Power supply, nominal 1.8V
20	Q_0	OUT	LVCMOS single-ended output
21	EPAD	GND	Connect to Ground.

## Test Loads



$R_s = 33\Omega$  for  $Z_o=50\Omega$

# Applications Diagram



## Electrical Characteristics–Absolute Maximum Ratings

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDDx		-0.5		2.5	V	1,2
Input Voltage	V <sub>IN</sub>		-0.5		V <sub>DD</sub> +0.5	V	1,3
Input High Voltage, SMBus	V <sub>IHSMB</sub>	SMBus clock and data pins			3.6	V	1
Storage Temperature	T <sub>s</sub>		-65		150	°C	1
Junction Temperature	T <sub>j</sub>				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Operation under these conditions is neither implied nor guaranteed.

<sup>3</sup>Not to exceed 2.5V.

## Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

T<sub>A</sub> = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Supply Voltage	VDD1.8	Supply voltage for core and analog	1.7	1.8	1.9	V	
Reference Supply Voltage	VDDREF_1.05	Reference for 1.05V inputs	0.8	1.05	1.1	V	
Ambient Operating Temperature	T <sub>AMB</sub>	Industrial range	-40	25	85	°C	
Input High Voltage	V <sub>IH</sub>	Control Inputs	0.75 V <sub>DD</sub>	1.6	V <sub>DD</sub> + 0.3	V	
Input Low Voltage	V <sub>IL</sub>	Control Inputs	-0.3	0.2	0.25 V <sub>DD</sub>	V	
Input Current	I <sub>IN</sub>	Single-ended inputs, V <sub>IN</sub> = GND, V <sub>IN</sub> = VDD	-5	0.0	5	uA	
	I <sub>INP</sub>	Single-ended inputs V <sub>IN</sub> = 0 V; Inputs with internal pull-up resistors V <sub>IN</sub> = VDD; Inputs with internal pull-down resistors	-200	0.0	200	uA	
Input Frequency	F <sub>in</sub>		1	24	48	MHz	
Pin Inductance	L <sub>pin</sub>				7	nH	1
Capacitance	C <sub>IN</sub>	Logic Inputs, except DIF_IN	1.5		5	pF	1
	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1
	C <sub>OUT</sub>	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1	ms	1,2
Input SS Modulation Frequency non-PCIe	f <sub>MODIN</sub>	Allowable Frequency for non-PCIe Applications (Triangular Modulation)	0		66	kHz	1
OE Latency	t <sub>LATOE#</sub>	Output start after OE assertion Output stop after OE deassertion	1		3	clocks	1
T <sub>fall</sub>	t <sub>F</sub>	Fall time of single-ended control inputs			5	ns	2
T <sub>rise</sub>	t <sub>R</sub>	Rise time of single-ended control inputs			5	ns	2

<sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

## Electrical Characteristics–Clock Input Parameters

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input High Voltage	V <sub>IH</sub>	ICLKx_1.05	800	1.0	VREF_1.05 + 200mV	mV	1
Input Low Voltage	V <sub>IL</sub>	ICLKx_1.05	-200	0	200	mV	1
Input Slew Rate	dv/dt	Single-ended measurement	0.5	-	5	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>DD</sub> , V <sub>IN</sub> = GND	-5	0	5	uA	
Input Duty Cycle	d <sub>tin</sub>	Measurement from differential waveform	45	50	55	%	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

## Electrical Characteristics–Q\_x 1.05V Single-ended Outputs

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on, CL=2pF	0.8	1.5	2.5	V/ns	1,2
		Scope averaging on, CL=4.7pF	0.5	1	1.5	V/ns	1,2
Voltage High	V <sub>HIGH</sub>	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on)	875	1000	1100	mV	
Voltage Low	V <sub>LOW</sub>		-150	0	150		

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Measured from 20% to 80% of swing

## Electrical Characteristics–Current Consumption

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I <sub>BDVref1.05</sub>	VREF_1.05V pin		0.07	0.5	mA	
	I <sub>DD1.8</sub>	VDD, All outputs active @24MHz, CL=2pF		8.2	12	mA	
Powerdown Current	I <sub>DDAPD</sub>	VREF_1.05V pin		0.07	0.5	mA	1
	I <sub>DDPD</sub>	VDD, All outputs disabled.		3.3	5	mA	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>1</sup> Input clock stopped.

## Electrical Characteristics–Output Duty Cycle, Jitter, and Skew Characteristics

TA = T<sub>AMB</sub>, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Duty Cycle Distortion	t <sub>DCD</sub>	@24MHz	-2	-0.8%	0	%	1,2
Skew, Input to Output	t <sub>I2O</sub>	V <sub>T</sub> = 50%	2000	2474	3000	ps	1
Skew, Output to Output	t <sub>o2oA</sub>	Within banks Q[3:0] or Q[7:4], V <sub>T</sub> = 50%		10	50	ps	1
Skew, Matching	t <sub>o2oB</sub>	Between banks Q[3:0] and Q[7:4], V <sub>T</sub> = 50%		47	100	ps	1
Jitter, Cycle to cycle	t <sub>ICYC-CYC</sub>	Additive Jitter, V <sub>T</sub> = 50%		3.5	8	ps	1

<sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>2</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

## Marking Diagram



### Notes:

1. "LOT" denotes the lot number.
2. "YYWW" is the last two digits of the year and week that the part was assembled.
3. Line 2: truncated part number
4. "L" denotes RoHS compliant package.
5. "I" denotes industrial temperature grade.

## Thermal Characteristics

PARAMETER	SYMBOL	CONDITIONS	PKG	TYP VALUE	UNITS	NOTES
Thermal Resistance	$\theta_{JC}$	Junction to Case	NLG20	42	°C/W	1
	$\theta_{Jb}$	Junction to Base		2.4	°C/W	1
	$\theta_{JA0}$	Junction to Air, still air		39	°C/W	1
	$\theta_{JA1}$	Junction to Air, 1 m/s air flow		33	°C/W	1
	$\theta_{JA3}$	Junction to Air, 3 m/s air flow		28	°C/W	1
	$\theta_{JA5}$	Junction to Air, 5 m/s air flow		27	°C/W	1

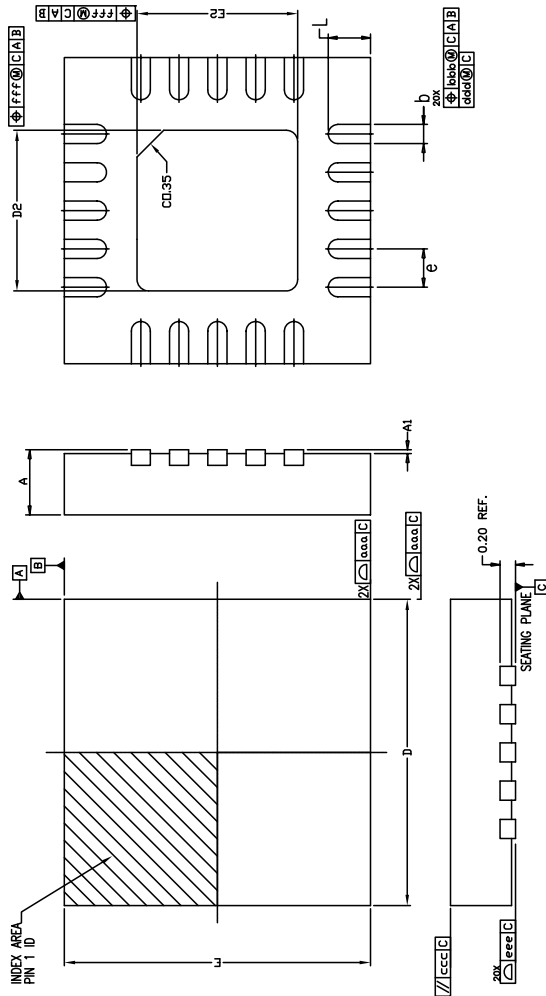
<sup>1</sup>ePad soldered to board

# Package Outline and Dimensions (NLG20)

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	5/19/16	JH

SYMBOL	DIMENSION		
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	1.95	2.10	2.25
E2	1.95	2.10	2.25
L	0.45	0.55	0.65
e	0.50 BSC		
N	20		
b	0.20	0.25	0.30
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

TOP VIEW      SIDE VIEW      BOTTOM VIEW



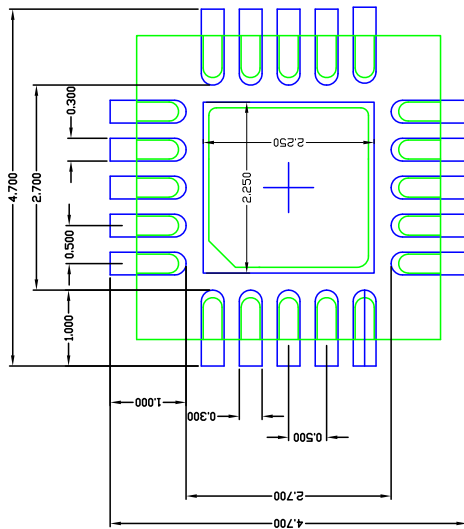
TOLERANCES UNLESS SPECIFIED: DECIMAL ±1% ANGULAR ±1° XXX± XXX±	APPROVALS _____ DATE _____ DRAWN $\emptyset$ MC 15/13/08 CHECKED _____	6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8991 www.IDT.com	
	TITLE: NLG 20 LEADS PACKAGE OUTLINE 4.0 x 4.0 mm BODY, EPAD 2.10mm SQ 0.50 mm PITCH VFQFP-N	SIZE: _____ DRAWING No. _____ PSC-4170-01	REV: _____ 00
	DO NOT SCALE DRAWING		SHEET 1 OF 2

NOTES:  
 1. ALL DIMENSIONS ARE IN MILLIMETERS.  
 2. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982.



Package Outline and Dimensions (NLG20), cont.

REVISIONS		
REV	DESCRIPTION	DATE
00	INITIAL RELEASE	5/19/16
		JH



RECOMMENDED LAND PATTERN DIMENSION

- NOTES:
1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
  2. TOP DOWN VIEW, AS VIEWED ON PCB.
  3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
  4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
  5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED IN DECIMAL	 6024 Silver Creek Valley Road San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591 www.IDT.com	TITLE	NLG 20 LEADS PACKAGE OUTLINE
±1		DATE	5/13/08
XX±	APPROVALS	DATE	5/13/08
XXX±	CHECKED		
	SIZE	DRAWING No.	PSC-4170-01
		REV	00
		DO NOT SCALE DRAWING	
		SHEET 2 OF 2	

## Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9SBV0802AKILF	Tubes	20-pin VFQFPN	-40° to +85°C
9SBV0802AKILFT	Tape and Reel	20-pin VFQFPN	-40° to +85°C

"LF" to the suffix denotes Pb-Free configuration, RoHS compliant.

"A" is the device revision designator (will not correlate with the datasheet revision).

## Revision History

Rev.	Issue Date	Initiator	Description	Page #
A	9/22/2015	RDW	<ol style="list-style-type: none"> <li>1. Corrected polarity of OE inputs to be active low instead of active high.</li> <li>2. Added 2pF test loads in addition to 4.7pF</li> <li>3. Updated electrical tables with preliminary data.</li> <li>4. Updated block diagram with proper OE polarity.</li> <li>5. Moved from Advance to Preliminary</li> </ol>	Various
B	12/15/2015	RDW	<ol style="list-style-type: none"> <li>1. Update front page text.</li> <li>2. Add Applications Diagram</li> <li>3. Update Electrical tables with characterization data</li> <li>4. Added "Output Duty Cycle, Jitter, and Skew Characteristics" Table</li> <li>5. Correct pin description for pin 9.</li> <li>6. Move to final.</li> </ol>	Various
C	12/15/2016	RDW	Updated POD drawings with latest showing 2.1 mm SQ. EPAD (PSC-4170-01)	8, 9



**Corporate Headquarters**  
6024 Silver Creek Valley Road  
San Jose, CA 95138 USA  
[www.IDT.com](http://www.IDT.com)

**Sales**  
1-800-345-7015 or 408-284-8200  
Fax: 408-284-2775  
[www.IDT.com/go/sales](http://www.IDT.com/go/sales)

**Tech Support**  
[www.idt.com/go/support](http://www.idt.com/go/support)

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Product specification subject to change without notice. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright ©2016 Integrated Device Technology, Inc.. All rights reserved.